

Certificate TW08/00313

SGS

The management system of

Unimicron Technology Corporation Hsinfeng I Plant

No. 289 & 290, Zhonglun Village, Xinfeng Township, Hsinchu County 304, Taiwan (R.O.C.)

has been assessed and certified as meeting the requirements of
ISO 14001:2015

For the following activities

Unimicron Technology Corporation Hsinfeng I Plant

The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(HF)

Unimicron Technology Corporation Dayuan Plant

The manufacture of printed circuit boards, High Density Interconnect (HDI) boards. (LC3)

Unimicron Technology Corporation Yangmei Plant

The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(YM)

Unimicron Technology Corporation Chung-Hsing Plant

Design and manufacture of projective - capacitive touch panels.(ZX)

This certificate is valid from 30 June 2023 until 30 June 2026 and remains valid subject to satisfactory surveillance audits.

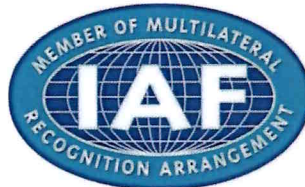
Issue 11. Certified since 30 June 2008

Certified activities performed by additional sites are listed on subsequent pages.

Jonathan H. Hall

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Certificate TW08/00313, continued

Unimicron Technology Corporation Hsinfeng I Plant

ISO 14001:2015

Issue 11
Sites
Unimicron Technology Corporation Hsinfeng I Plant No. 289 & 290, Zhonglun Village, Xinfeng Township, Hsinchu County 304, Taiwan (R.O.C.) The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(HF)
Unimicron Technology Corporation Dayuan Plant No.5, Minquan Rd., Dayuan Dist., Taoyuan City 337, Taiwan (R.O.C.) The manufacture of printed circuit boards, High Density Interconnect (HDI) boards. (LC3)
Unimicron Technology Corporation Yangmei Plant No.66.68.70 ,Ln 426, Sec.1, Meishi Rd. Yangmei Dist., Taoyuan City 326, Taiwan (R.O.C.) The manufacture of IC carriers including substrates for all Grid Array (BGA), Land Grid Array (LGA) and Flip Chip package.(YM)
Unimicron Technology Corporation Chung-Hsing Plant No.669, Sec. 4, Chung-Hsing Road, Chu-Dung, Hsin-Chu County, Taiwan, 310, R.O.C. Design and manufacture of projective - capacitive touch panels.(ZX)



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